Power MOSFET 40 V, 0.82 mΩ, 330 A, Single N–Channel

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS	(T _J = 25°	C unless otherv	vise noted)		
Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	40	V
Gate-to-Source Voltage			V _{GS}	±20	V
Continuous Drain		$T_C = 25^{\circ}C$	۱ _D	330	А
Current $R_{\theta JC}$ (Notes 1, 3)	Steady State	T _C = 100°C		230	
Power Dissipation		$T_C = 25^{\circ}C$	PD	139	W
R _{θJC} (Note 1)		$T_{C} = 100^{\circ}C$		56	
Continuous Drain	Steady	$T_A = 25^{\circ}C$	۱ _D	50	А
Current R _{0JA} (Notes 1, 2, 3)		$T_A = 100^{\circ}C$		35	
Power Dissipation	State	T _A = 25°C	PD	3.2	W
$R_{\theta JA}$ (Notes 1 & 2)		$T_A = 100^{\circ}C$		1.3	
Pulsed Drain Current	T _A = 25	°C, t _p = 10 μs	I _{DM}	900	А
Operating Junction and Storage Temperature			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)			۱ _S	162	А
Single Pulse Drain–to–Source Avalanche Energy (I _{L(pk)} = 29 A)			E _{AS}	706	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			ΤL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{ extsf{ heta}JC}$	0.9	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	39	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.

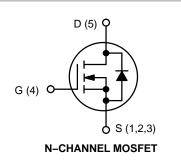
3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

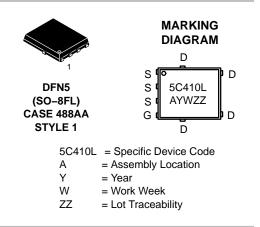


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V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
40 V	0.82 mΩ @ 10 V	220.4
40 V	1.2 mΩ @ 4.5 V	330 A





ORDERING INFORMATION

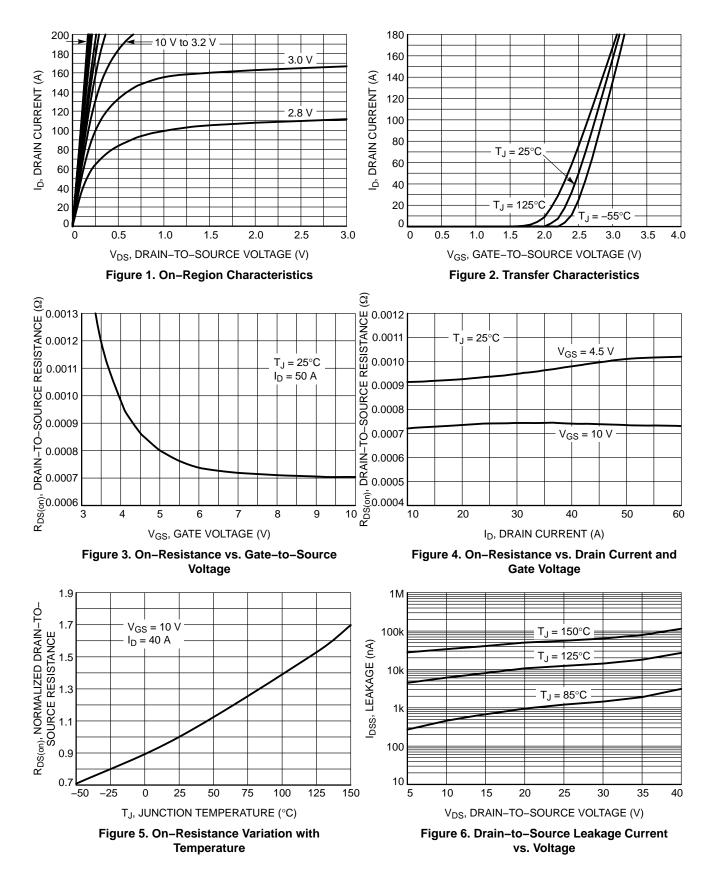
See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J = 25° C unless otherwise specified)

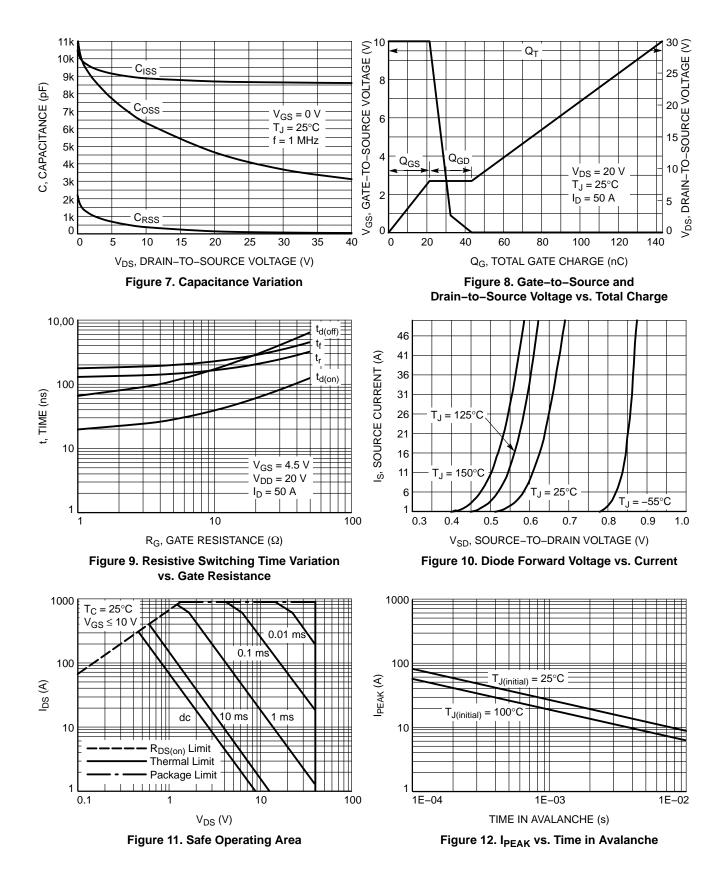
Parameter	Symbol	Test Condi	tion	Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 V, I_D = 250 \mu A$		40			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} / T _J				21.2		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,	T _J = 25 °C			10	
		V _{DS} = 40 V	T _J = 125°C	C 250 ^µ	μΑ		
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = 20 V				100	nA
ON CHARACTERISTICS (Note 4)				-			-
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = 250 \ \mu A$		1.2		2.0	V
Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-5.75		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 50 A		0.65	0.82	mΩ
		V _{GS} = 4.5 V	I _D = 50 A		0.95	1.2	
Forward Transconductance	9 _{FS}	V _{DS} = 15 V, I _D = 50 A			190		S
CHARGES, CAPACITANCES & GATE RE	SISTANCE						
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 25 V			8862		pF
Output Capacitance	C _{OSS}				4156		
Reverse Transfer Capacitance	C _{RSS}				116		
Total Gate Charge	Q _{G(TOT)}	V_{GS} = 4.5 V, V_{DS} = 20 V; I_{D} = 50 A			66		
Total Gate Charge	Q _{G(TOT)}	V_{GS} = 10 V, V_{DS} = 20 V; I_{D} = 50 A			143		1
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 4.5 V, V _{DS} = 20 V; I _D = 50 A			6.75		nC
Gate-to-Source Charge	Q _{GS}				21.4		
Gate-to-Drain Charge	Q _{GD}				22		
Plateau Voltage	V _{GP}				2.7		V
SWITCHING CHARACTERISTICS (Note 5	5)						
Turn-On Delay Time	t _{d(ON)}	V_{GS} = 4.5 V, V_{DS} = 20 V, I _D = 50 A, R _G = 1.0 Ω			20		ns
Rise Time	t _r				130		
Turn-Off Delay Time	t _{d(OFF)}				66		
Fall Time	t _f				177		
DRAIN-SOURCE DIODE CHARACTERIS	TICS						
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V,	$T_J = 25^{\circ}C$		0.73	1.2	
	$I_{\rm S} = 50$ Å	T _J = 125°C		0.6		V	
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, dIS/dt = 100 A/µs, I _S = 50 A			79.5		
Charge Time	ta				39		ns
Discharge Time	t _b				40.5		
Reverse Recovery Charge	Q _{RR}			1	126		nC

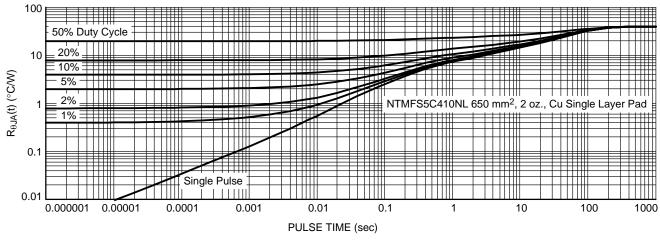
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Pulse Test: pulse width $\leq 300 \ \mu$ s, duty cycle $\leq 2\%$. 5. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS





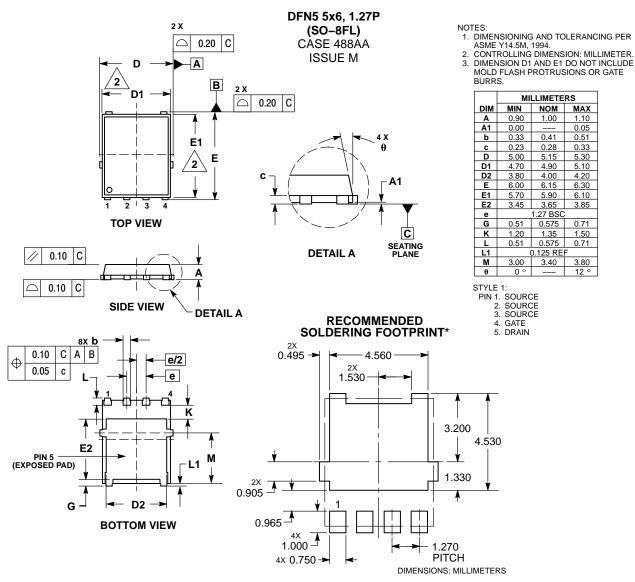


DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NTMFS5C410NLT1G	5C410L	DFN5 (Pb–Free)	1500 / Tape & Reel
NTMFS5C410NLT3G	5C410L	DFN5 (Pb–Free)	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT

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